1.6x0.8mm SMD CHIP LED LAMP



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

APHK1608PWC

WHITE

Features

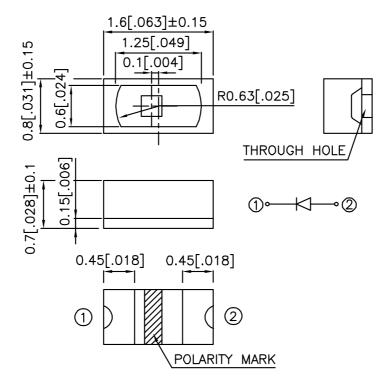
- ●1.6mmx0.8mm SMT LED, 0.7mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACK LIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- ●PACKAGE: 2000PCS / REEL.

Description

The source color devices are made with InGaN on SiC Light Emitting Diode.

Static electricity and surge damage the LEDS. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

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APPROVED: J. Lu CHECKED: Allen Liu DRAWN: S.J.HOU

Selection Guide

Part No.	Dice	Lens Type	lv (m @ 20	,	Viewing Angle
			Min. Typ.		201/2
APHK1608PWC	WHITE (InGaN)	WATER CLEAR	70	150	90°

Note:

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
VF	Forward Voltage	White	3.65	4.2	V	IF=20mA
IR	Reverse Current	White		10	uA	VR = 5V
Х	Observativity Opension to	White	0.33			
Y	Chromaticity Coordinates		0.34			
С	Capacitance	White	65		pF	VF=0V;f=1MHz

Absolute Maximum Ratings at Ta=25°C

Parameter	White	Units	
Power dissipation	102	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		

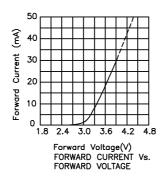
Note

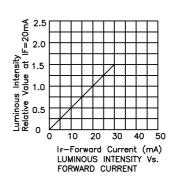
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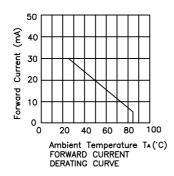
^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

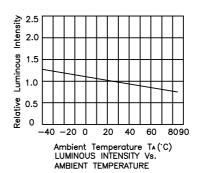
^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

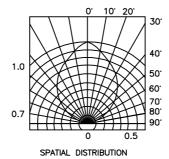












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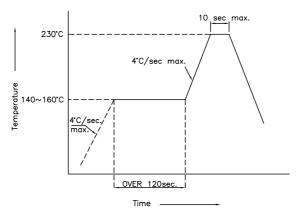
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APHK1608PWC

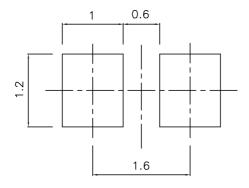
SMT Reflow Soldering Instruction

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



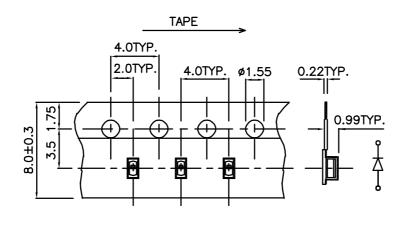
Recommended Soldering Pattern

(Units: mm)



Tape Specifications

(Units: mm)



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